Cypress CYV15G0403DXB HOTLink II Video Demonstration Board

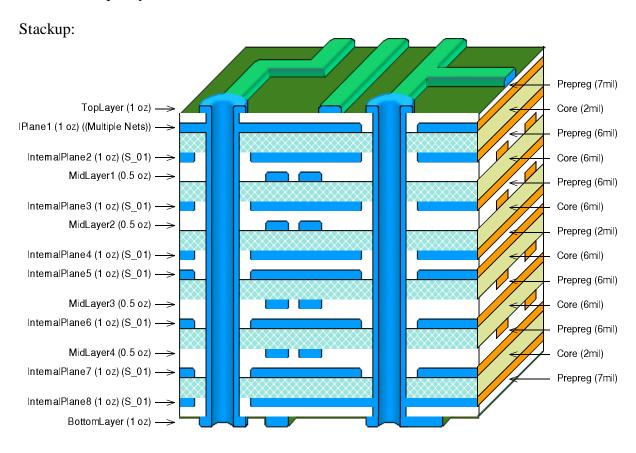
February 25, 2004

Board size: 6" x 8" Thickness: 84 +0/-2 mil

Material: FR-408

Solder mask: LPI, both sides Silkscreen: white, both sides Hot air solder level (SMOBC): yes

Bare board test: yes Commercial quality



- · we don't care which dielectric layers are core and which are prepreg
- 5.067mil traces on MidLayer1 and MidLayer4 should have 50 ohm characteristic impedance
- 12.343mil traces on TopLayer and BottomLayer should have 50 ohm characteristic impedance
- 5.564mil traces on TopLayer and BottomLayer should have 75 ohm characteristic impedance
- pair of 13.59mil traces on TopLayer should have 90 ohm differential impedance

Contents of molson20040223.zip:

MolsonPCB.DRL	Excellon drill file	binary
MolsonPCB.DRR	NC drill report	text
MolsonPCB.G1	MidLayer1	RS274-X
MolsonPCB.G2	MidLayer2	RS274-X
MolsonPCB.G3	MidLayer3	RS274-X
MolsonPCB.G4	MidLayer4	RS274-X
MolsonPCB.GBL	BottomLayer	RS274-X
MolsonPCB.GBO	BottomOverlay	RS274-X
MolsonPCB.GBP	BottomPaste	RS274-X
MolsonPCB.GBS	BottomSolder	RS274-X
MolsonPCB.GP1	InternalPlane1	RS274-X
MolsonPCB.GP2	InternalPlane2	RS274-X
MolsonPCB.GP3	InternalPlane3	RS274-X
MolsonPCB.GP4	InternalPlane4	RS274-X
MolsonPCB.GP5	InternalPlane5	RS274-X
MolsonPCB.GP6	InternalPlane6	RS274-X
MolsonPCB.GP7	InternalPlane7	RS274-X
MolsonPCB.GP8	InternalPlane8	RS274-X
MolsonPCB.GTL	TopLayer	RS274-X
MolsonPCB.GTO	TopOverlay	RS274-X
MolsonPCB.GTP	TopPaste	RS274-X
MolsonPCB.GTS	TopSolder	RS274-X
MolsonPCB.TXT	Excellon drill file	text

There are four unplated 156mil tooling holes.